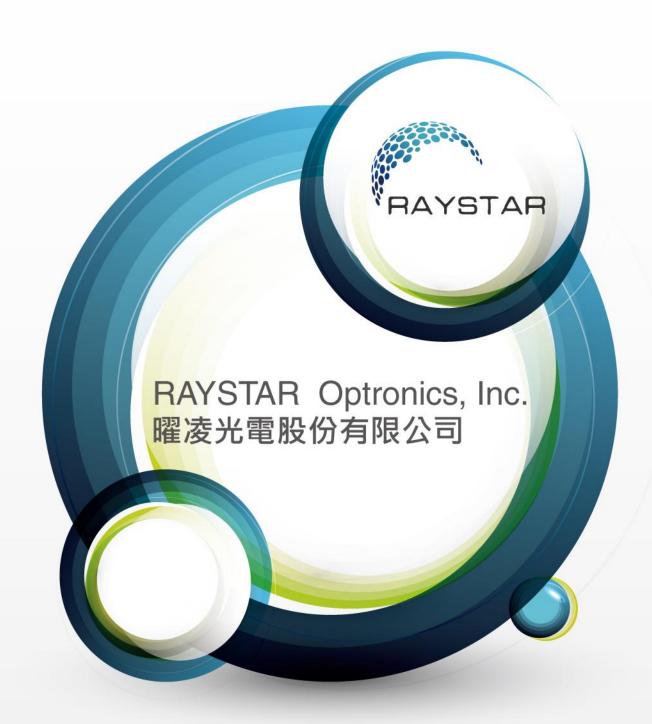
LCD / LCM SPECIFICATION





曜 凌 光 電 股 份 有 限 公 司 Raystar Optronics, Inc.

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RX12864U-FHW

SPECIFICATION

CUSTOMER:

APPROVED BY
PCB VERSION
DATE

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2019/06/03		First issue
А	2019/09/29		Modify Material List of Components for
			RoHs
В	2019/12/30		Modify Precautions in
			use of LCD Modules



Contents

- 1.General Specification
- 2. Module Classification Information
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- 4. Contour Drawing
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- 9.Reliability
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- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13.Recommendable Storage



1.General Specification

The Features of the Module is description as follow:

■ Number of dots: 128 x 64

■ Module dimension: 58.2 x 44.7 x 3.9(MAX) mm

View area: 52.0 x 33.5 mm

Active area: 47.76 x 30.29 mm

■ Dot size: 0.40 x 0.35 mm

■ Dot pitch: 0.42 x 0.37 mm

■ LCD type: FSTN Positive Transflective

■ Duty: 1/64

View direction: 6 o'clock

■ Backlight Type: LED, White

■ IC: ST7565P



2. Module Classification Information

<u>R</u>	<u>X</u>	<u>12864</u>	<u>U</u>	_	<u>F</u>	<u>H</u>	W
①	2	3	4		(5)	6	7

Item			escription	on			
1	R: Raystar O	aystar Optronics Inc.					
2	Diaplay	C: Character Type,		T:TAB Type			
2	Display	G: Graphic Type		X:COG Type			
3	Display Font :	128 * 64 dot					
4	Serials code:						
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue		
		N→TN Negative,		T→FSTN Ne	egative, Black		
		L→VA Negative		D→FSTN N	egative (Double film)		
		H→ HTN Positive, Gray		F→FSTN Po	ositive		
5	LCD	I→HTN Negative, Black		K→FSC Neg	gative		
		U→HTN Negative, Blue		S→FSC Pos	sitive		
		B→STN Negative, Blue		E→ISTN Ne	gative, Black		
		G→STN Positive, Gray		C→CSTN Negative, Black			
		Y→STN Positive, Gray Y→STN Positive, Yellow Green A: Reflective, N.T, 6:00		A→ASTN Negative, Black			
		A: Reflective, N.T, 6:00	A: Reflective, N.T, 6:00		ctive, W.T,12:00		
	Polarizer	D: Reflective, N.T, 12:0	0	1: Transfled	ctive, U.T,6:00		
	Type,	G: Reflective, W. T, 6:00)	4: Transflective, U.T.12:00			
	Temperature	J: Reflective, W. T, 12:0	0	C: Transmissive, N.T,6:00			
6	range,	0: Reflective, U. T, 6:00		F: Transmis	ssive, N.T,12:00		
	90,	3: Reflective, U. T, 12:0	0	I: Transmis	sive, W. T, 6:00		
	View	B: Transflective, N.T,6:0		L: Transmis	ssive, W.T,12:00		
	direction	E: Transflective, N.T.12	:00	2: Transmissive, U. T, 6:00			
		H: Transflective, W.T,6:			sive, U.T,12:00		
		N→ Without backlight	W→LE	D, White	G→LED, Green		
		P→EL, Blue	A→LED	•	S→LED, Full color		
		T→EL, Green	R→LED	, Red	J→DIP LED, Blue		
7	Backlight	D→EL, White), Orange	K→DIP LED, White		
,	Buokiight	M→EL, Yellow Green	B→LED	•	E→DIP LED, Yellow		
	7	F→CCFL, White		, Dual color	L→DIP LED, Amber		
		Y→LED, Yellow Green	C→LED	, Full color	I→DIP LED, Red		



3.Interface Pin Function

Pin No.	Symbol	I/O				Description			
1	VDD	_	Power	Power supply pin for logic.					
2	VSS	_	Groun	d pin, conne	ected to	0V			
3	/CS1		Chip s	elect input p	in. Inter	face access is enabled when CS1B is "L"			
4	CS2	I		B2 is "H". W pins are hig		p is non-active (CS1B="H" or CS2="L"), dance.			
5	/RES	I			-	When RSTB is "L", internal initialization all registers will be initialized.			
6	A0	I	It dete A0="H A0="L"	rmines whet ": Indicates ': Indicates t	ther the that sign that sign	access is related to data or command. nals on D[7:0] are display data. nals on D[7:0] are command.			
			l —		- `	trol pin. When PSB is "H",			
			C86	MPU Type	RWR	Description			
		I	н	6800 series	R/W	Read/Write control input pin.			
7	R/W					R/W="H": read.			
	FC/VV					R/W="L": write.			
			8080		WR	Write enable input pin. Signals on D[7:0] will be latched at the rising			
				series	/ / / / /	edge of /WR signal.			
			DWD:		1				
						interface and should fix to "H" by VDD.			
						trol pin. When PSB is "H",			
	. 1		C86	MPU Type	ERD	Description			
	1					Read/Write control input pin.			
				6800		R/W="H": When E is "H", D[7:0] are in output			
8	E	ı	H	series	E	mode.			
						R/W="L": Signals on D[7:0] are latched at the			
				2000		falling edge of E signal.			
			L	8080	/RD	Read enable input pin.			
			series When /RD is "L", D[7:0] are in output mode.						
			ERD is not used in serial interface and should fix to "H" by VDD.						
9-16	D0-D7	I/O	Data b	us line					

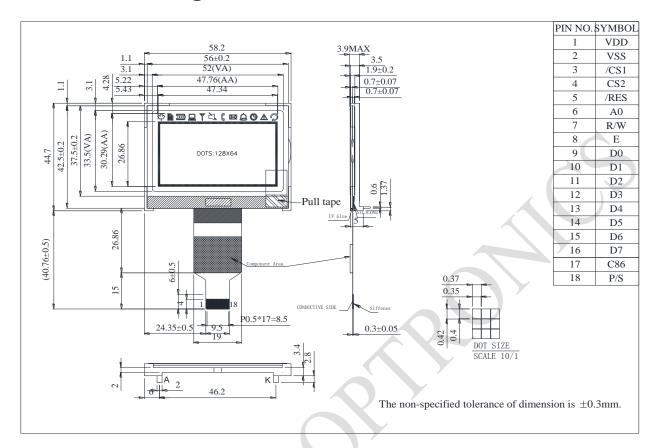




			C86 selects	the micropr	ocessor type in parallel interface mode.		
			PSB	C86	Selected Interface		
	17 C86 I	"H"	"H"	Parallel 6800 Series MPU Interface			
17			"H"	"L"	Parallel 8080 Series MPU Interface		
''			"L"	"X"	Serial 4-Line SPI Interface		
			Please refer to "APPLICATION NOTES" and "Microprocessor Interface" (Section 6) for detailed connection of the selected interface.				
18	P/S	I	PSB selects the interface type: Serial or Parallel.				



4. Contour Drawing



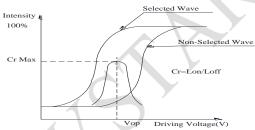


5.Optical Characteristics

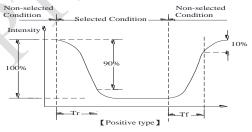
Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	30	ψ= 180°
View Angle	θ	CR≧2	0	_	60	ψ= 0°
View Angle	θ	CR≧2	0	_	45	ψ= 90°
	θ	CR≧2	0	_	45	ψ= 270°
Contrast Ratio	CR	_	_	5	7)	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	Q.	250	350	ms

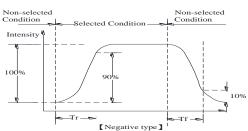
Definition of Operation Voltage (Vop)

Intensity Non-Selected Wave Non-Selected Wave Cr Max Vop Driving Voltage(V)



Definition of Response Time (Tr, Tf)

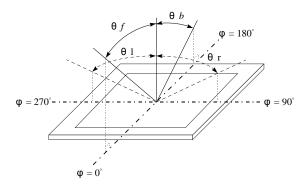




Conditions:

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)





6.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T _{ST}	-30	_	+80	C
Power Supply Voltage	VDD	-0.3	_	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	-	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3		V0+0.3	٧



7. Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	3.0	_	3.3	V
		Ta=-20℃		_	-	V
Supply Voltage For LCD	V_{OP}	Ta=25℃	8.3	8.5	8.7	V
		Ta=70℃				V
Input High Volt.	V_{IH}	_	0.8V _{DD}		V_{DD}	V
Input Low Volt.	V_{IL}	_	V_{SS}		0.2V _{DD}	V
Output High Volt.	V_{OH}	_	0.8V _{DD}		V_{DD}	V
Output Low Volt.	V_{OL}	_	V_{DD}	_	0.2V _{DD}	V
Supply Current	I _{DD}	V _{DD} =3.3V	7	1	2	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.



8.Backlight Information

Specification

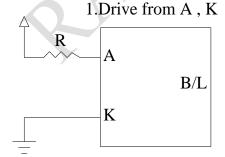
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION	
Supply Current	ILED	36	48	60	mA	V= 3.5V	
Supply Voltage	V	_	3.5	_	V	-	
Reverse Voltage	VR	_	_	5	V	- 10	
Color	Х	0.25	0.28	0.31		II ED 40A	
coordinate	Y	0.27	0.30	0.33	_ (ILED=48mA	
Luminance	IV	688	960		CD/M²	ILED=48mA	
(Without LCD)	10	000	860		CD/IVI	ILED=46IIIA	
LED Life Time	_	30K	Ć	R	Hr.	ILED=48mA 25℃,50-60%RH, (Note 2)	
Color	White						

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: Supply current minimum value is only for reference since LED brightness efficiency keeps enhancing. Current consumption becomes less and less to achieve the same luminance.

Note2:30K hours is only an estimate for reference.

LED B\L Drive Method





9. Reliability

Content of Reliability Test (Wide temperature, -20℃~70℃)

	Environmental Test							
Test Item	Content of Test	Test Condition	Note					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2					
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs						
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1					
High Temperature/ Humidity storage	The module should be allowed to stand at 40 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	40℃,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles						
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times						

Note1: No dew condensation to be observed.

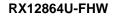
Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



10.Inspection specification

NO	Item			Criterion		AQL
01	Electrical Testing	 1.1 Missing vertical, horized defect. 1.2 Missing character, defect. 1.3 Display malfunction. 1.4 No function or no display to the consumption. 1.5 Current consumption. 1.6 LCD viewing angle defect. 		t or icon. lay. exceeds product sp	0.65	
		1.7 Mixed produ 1.8 Contrast def	• •			
02	Black or white spots on LCD (display only)	2.1 White and bl	2.1 White and black spots three white or black spots 2.2 Densely spaced: No me		7	2.5
03	LCD black spots, white	3.1 Round type $\Phi = (x + y) / x$ $\longrightarrow X$	² ↓ T Y	ving drawing SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0	2.5
			As followin Length L≦3.0 L≦2.5 	width W≦0.02 0.02 <w≦0.03 0.03<w≦0.05="" 0.05<w<="" td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w≦0.03>	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are vis judge using blace specifications, n to find, must che specify direction	k spot ot easy eck in	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5





NO	Item	Criterion A(
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
		Symbols Define:			
		x: Chip length y:	Chip width z: Chip to	thickness	
		k: Seal width t:	Glass thickness a: LCD	side length	
		L: Electrode pad length	ո:		
		6.1 General glass chip	:		
		6.1.1 Chip on panel su	rface and crack between	panels:	
			Y K		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing	x≦1/8a	
06	Chipped		area		2.5
	glass	1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		 ⊙If there are 2 or more 6.1.2 Corner crack:	e chips, x is total length o	of each chip.	
	1	z: Chip thickness	y: Chip width	x: Chip length	
	K 7	Z≦1/2t	Not over viewing	x≦1/8a	
		_= '/	area	Λ <u>=</u> // 0 α	
		1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a	
	⊙ If there are 2 or more chips, x is the total length of each ch				



NO	Item	Criterion						
		Symbols :						
			Chip thickness					
		k: Seal width t: Glass thickness a	•					
		L: Electrode pad length	3.					
		6.2 Protrusion over terminal :						
		6.2.1 Chip on electrode pad :						
		·						
			2					
			AX.					
		y: Chip width x: Chip length	z: Chip thickness					
		y≤0.5mm x≤1/8a	$0 < z \le t$					
		6.2.2 Non-conductive portion:						
		·						
06	Glass			2.5				
	crack		12					
		y	Y					
		X	X					
		y: Chip width x: Chip ler	gth z: Chip thickness					
		y≦ L x≦1/8a	$0 < z \le t$					
		⊙If the chipped area touches the IT	O terminal, over 2/3 of the ITO					
		must remain and be inspected ac						
		specifications.	•					
		⊙If the product will be heat sealed	by the customer, the alignment					
		mark not be damaged.						
		6.2.3 Substrate protuberance and internal	crack.					
		X	vidth x: length					
			$\frac{1}{3L}$ $x \le a$					
			ı, σ .					
		,						
		•						



NO	Item	Criterion	AQL		
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5		
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.			
		 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 	2.5 2.5 0.65 2.5		
10	PCB · COB	 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 0.65 0.65		
		X * Y<=2mm2	2.5		
11	Soldering	11.1 No un-melted solder paste may be present on the PCB.11.2 No cold solder joints, missing solder connections, oxidation or icicle.	2.5 2.5		
		11.3 No residue or solder balls on PCB.11.4 No short circuits in components on PCB.	2.5 0.65		





	NO	Item	Criterion	AQL	
			12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5	
			12.2 No cracks on interface pin (OLB) of TCP.	0.65	
			12.3 No contamination, solder residue or solder balls on product.	2.5	
			12.4 The IC on the TCP may not be damaged, circuits.	2.5	
			12.5 The uppermost edge of the protective strip on the interface	2.5	
			pin must be present or look as if it cause the interface pin to sever.		
	12	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5	
		appearance	component) is not burned into brown or black color.	2.5	
			12.7 Sealant on top of the ITO circuit has not hardened.	0.65	
			12.8 Pin type must match type in specification sheet.	0.65	
			12.9 LCD pin loose or missing pins.	0.65	
			12.10 Product packaging must the same as specified on		
			packaging specification sheet.	0.65	
			12.11 Product dimension and structure must conform to product specification sheet.		
			12.12 Visual defect outside of VA is not considered to be rejection.		



11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.



12.Material List of Components for RoHs

1. RAYSTAR Optronics. Inc. hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limited value is set up according to RoHS.										

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : $235\pm5^{\circ}$

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.



13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

	LCM Sample	Estimate Feedback Sheet				
Module Number:						
1 · Panel Specification :						
1. Panel Type:	□ Pass	□ NG ,				
2. View Direction:	□ Pass	□ NG ,				
3. Numbers of Dots:	□ Pass	□ NG ,				
4. View Area:	□ Pass	□ NG ,				
5. Active Area :	□ Pass	□ NG ,				
6.Operating Temperature :	□ Pass	□ NG ,				
7.Storage Temperature :	□ Pass	□ NG ,				
8.Others:						
2 · Mechanical Specification :						
1. PCB Size :	□ Pass	□ NG ,				
2.Frame Size :	□ Pass	□ NG ,				
3.Materal of Frame:	□ Pass	□ NG ,				
4.Connector Position:	□ Pass	□ NG ,				
5.Fix Hole Position:	□ Pass	□ NG ,				
6.Backlight Position:	□ Pass	□ NG ,				
7. Thickness of PCB:	□ Pass	□ NG ,				
8. Height of Frame to PCB:	□ Pass	□ NG ,				
9.Height of Module:	□ Pass	□ NG ,				
10.Others:	□ Pass	□ NG ,				
3 · Relative Hole Size :						
1.Pitch of Connector:	□ Pass	□ NG ,				
2.Hole size of Connector:	□ Pass	□ NG ,				
3.Mounting Hole size:	□ Pass	□ NG ,				
4.Mounting Hole Type:	□ Pass	□ NG ,				
5.Others:	□ Pass	□ NG ,				
4 · Backlight Specification :						
1.B/L Type:	□ Pass	□ NG ,				
2.B/L Color:	□ Pass	□ NG ,				
3.B/L Driving Voltage (Reference for LED Type) : □ Pass □ NG ,						
4.B/L Driving Current:	□ Pass	□ NG ,				
5.Brightness of B/L:	□ Pass	□ NG ,				
6.B/L Solder Method:	□ Pass	□ NG ,				
7.Others:	□ Pass	□ NG ,				

>> Go to page 2 <<



Page: 2

Module Number :						
5 · Electronic Characteristics of Module :						
1.Input Voltage:	□ Pass	□ NG ,				
2.Supply Current:	□ Pass	□ NG ,				
3.Driving Voltage for LCD:	□ Pass	□ NG ,				
4.Contrast for LCD:	□ Pass	□ NG ,				
5.B/L Driving Method:	□ Pass	□ NG ,				
6.Negative Voltage Output:	□ Pass	□ NG ,				
7.Interface Function:	□ Pass	□ NG ,				
8.LCD Uniformity:	□ Pass	□ NG ,				
9.ESD test:	□ Pass	□ NG ,				
10.Others:	□ Pass	□ NG ,				
6 · <u>Summary</u> :						
Sales signature :						
	Customer Signature : Date : / /					
		-				